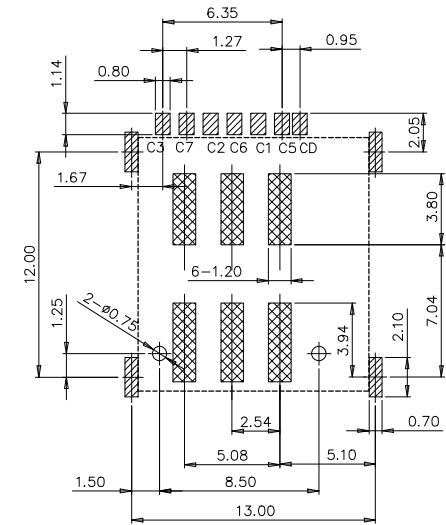
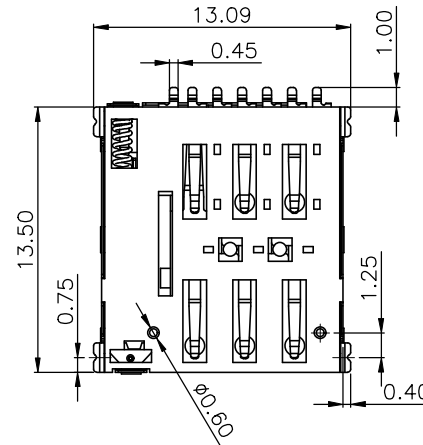
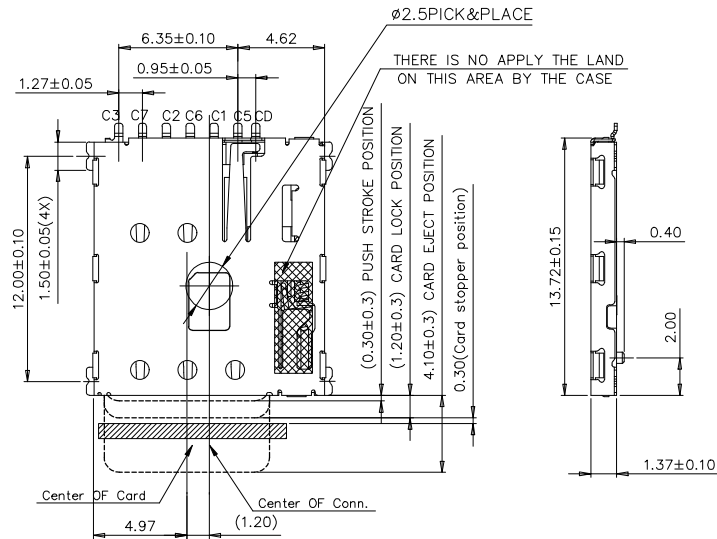




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

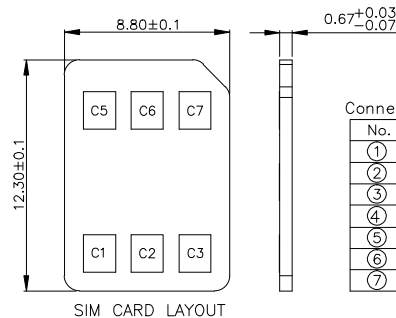
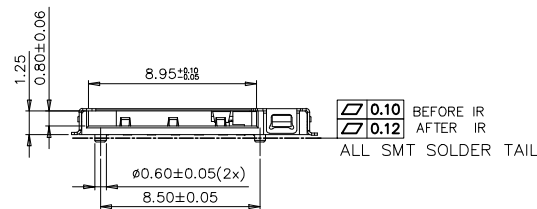
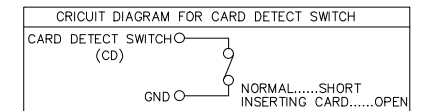


RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12MM

NOTES:

- MATERIAL:
HOUSING: HI-TEMP. PLASTIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- PLATING:
TERMINAL:
CONTACT AREA: AU GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±5/-5℃ 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature: -40℃~+85℃
Humidity 80% R.H MAX

- THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
- SMT SOLDER AREA



Connector Pin Assignment		
No.	Pin Name	Description
①	C1	Vcc of SIM
②	C2	RST of SIM
③	C3	CLK of SIM
④	C5	GND of SIM
⑤	C6	Vpp of SIM
⑥	C7	I/O of SIM
⑦	SW	Detection Switch

⑥	HOOK	SUS304	NO PLATING	1
⑤	SPRING	SUS	NO PLATING	1
④	SLIDE	PA46	GLASS FILLED(OR EQUAL), UL 94V-0, BLACK	1
③	SHELL	STAINLESS STEEL	GOLD FLASH PLATED ON SOLDER TAIL AREA. NICKEL 30~100u" UNDER PLATED OVER ALL	1
②	TERMINAL	COPPER ALLOY	GOLD PLATED ON CONTACT AREA"A" SEE "PLATED CODE NOTE" GOLD FLASH PLATED ON CONTACT AREA"B" AND SOLDER TAIL AREA NICKEL 50~150u" UNDER PLATED OVER ALL	1
①	HOUSING	LCP	GLASS FILLED(OR EQUAL), UL 94V-0, BLACK	1
ITEM	DESCRIPTION	MATERIAL	FINISH	Q'TY

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.20 X.XX :±0.10

ANGLES: X :±2° X.X :±1°



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	6Pin 1.37H PUSH PUSH Nano SIM CARD CONN.			
DWN	xiong	PART NO. SNO-1351		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	
CUSTOMER COPY				